



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Won Sun Shin, DoSung Chun, SangHo Lee, SeonGoo Lee, Vincent DiCaprio
Assignee: Amkor Technology, Inc.
Title: Semiconductor Package And Method For Fabricating The Same
Serial No.: 09/574,541 Filing Date: May 19, 2000
Examiner: C. Luu Group Art Unit: 2825
Batch No.: M03 Date Allowed: 9/17/01
Docket No.: AB-975 US

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BOX ISSUE FEE
COMMISSIONER FOR PATENTS
Washington, D. C. 20231

San Jose, California
December 3, 2001

**AMENDMENT AFTER ALLOWANCE
PURSUANT TO 37 C.F.R. §1.312**

Dear Sir:

Pursuant to 37 C.F.R. § 1.312 and co-incident with the payment of the issue fee, Applicants respectfully request the entrance of an amendment to the specification.

IN THE SPECIFICATION

Please replace the paragraph beginning at page 25, line 6 with the following rewritten paragraph. Attached hereto is a marked-up version of the changes made to the specification by the current amendment. The attached page is captioned "Version with markings to show changes made."

Other embodiments of semiconductor packages and methods of making them are disclosed in U.S. Patent Application Serial Number 09/566,069, which was filed with the U.S. Patent and Trademark Office on May 5, 2000, and in U.S. Patent Application Serial Number

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